

20V P-Channel Enhancement MOSFET

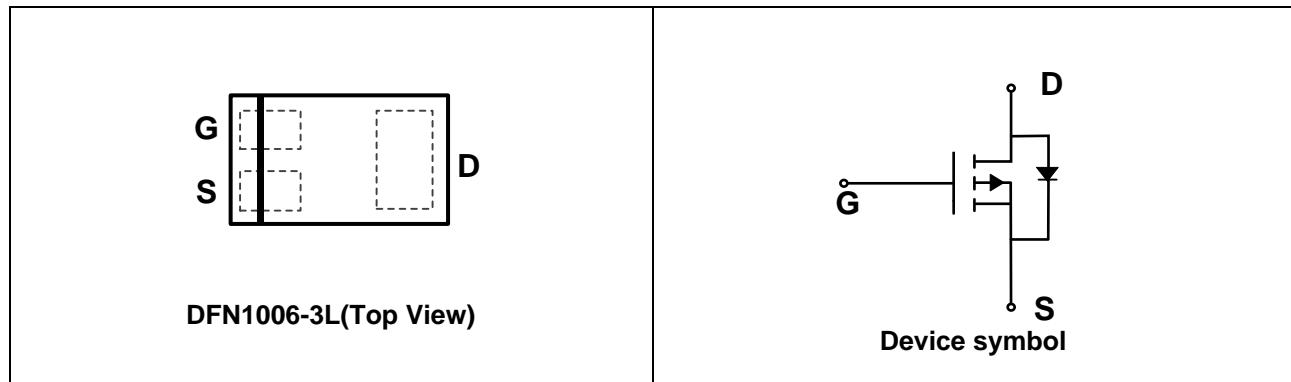
Features

- $V_{DS} = -20V$, $I_D = -1.8A$
 $R_{DS(on)} < 135m\Omega$ @ $V_{GS} = -4.5V$
 $R_{DS(on)} < 180m\Omega$ @ $V_{GS} = -2.5V$
- Trench LV MOSFET Technology

Mechanical Characteristics

- DFN1006-3L Package
- Marking: Marking Code
- RoHS Compliant

Schematic & PIN Configuration



EM02P18F

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current ⁽¹⁾	I_D	-1.8	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	-7.2	A
Power Dissipation	P_D	0.7	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ⁽²⁾	$R_{\theta JA}$	179	$^\circ\text{C}/\text{W}$

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Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-20	-	-	V
Gate-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 10\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$	-	-	-1	μA
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-	-1.0	V
Drain-Source on-state Resistance ⁽³⁾	$R_{DS(\text{on})}$	$V_{GS} = -4.5\text{V}, I_D = -1.7\text{A}$	-	112	135	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -1.2\text{A}$	-	149	180	
		$V_{GS} = -1.8\text{V}, I_D = -1.0\text{A}$	-	207	250	
Dynamic Characteristics ⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = -10\text{V}, f = 1\text{MHz}$	-	168	-	pF
Output Capacitance	C_{oss}		-	30	-	
Reverse Transfer Capacitance	C_{rss}		-	24	-	
Switching Characteristics ⁽⁴⁾						
Total Gate Charge	Q_g	$V_{GS} = -4.5\text{V}, V_{DS} = -10\text{V}, I_D = -1.7\text{A}$	-	2.72	-	nC
Gate-Source Charge	Q_{gs}		-	0.49	-	
Gate-Drain Charge	Q_{gd}		-	0.57	-	
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{GS} = -4.5\text{V}, V_{DD} = -10\text{V}, R_G = 3\Omega, I_D = -1.7\text{A}$	-	6.5	-	ns
Rise Time	t_r		-	4.8	-	
Turn-Off Delay Time	$t_{d(\text{off})}$		-	18	-	
Fall Time	t_f		-	5	-	
Source-Drain Body Diode Characteristics						
Body Diode Voltage ⁽³⁾	V_{SD}	$I_S = -1\text{A}, V_{GS} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	I_S		-	-	-1.8	A

Note1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$

Note2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

Note3. Pulsed Test: Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

Note4. This value is guaranteed by design hence it is not included in the production test.

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Typical Characteristics

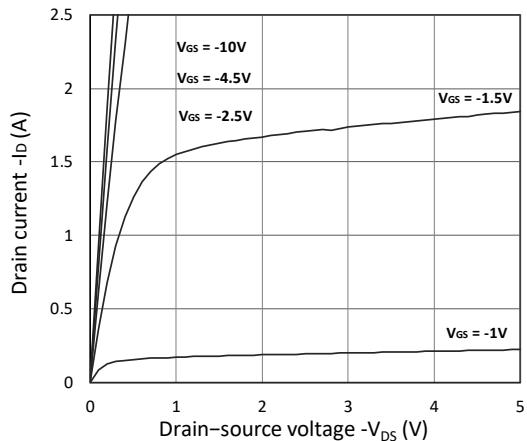


Figure 1. Output Characteristics

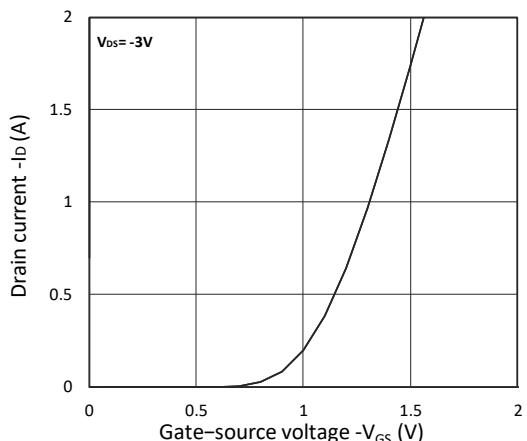


Figure 2. Transfer Characteristics

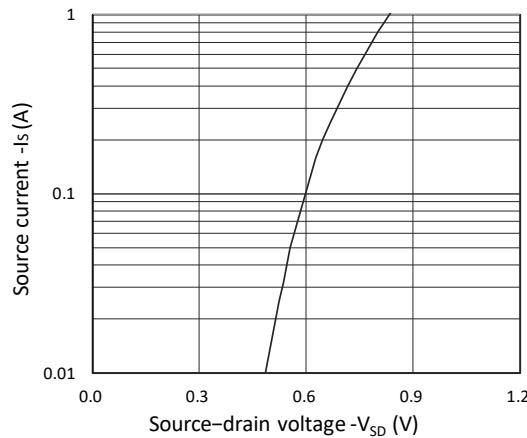


Figure 3. Forward Characteristics of Reverse

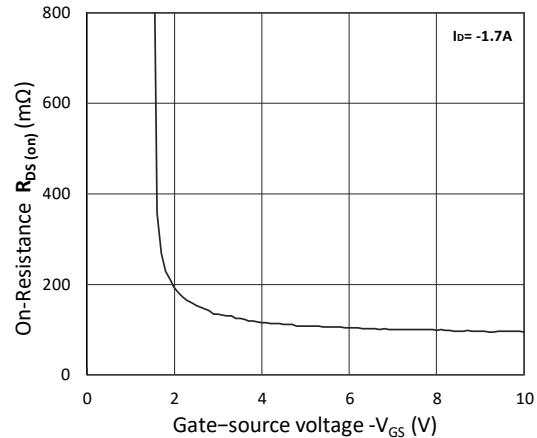


Figure 4. $R_{DS(on)}$ vs. V_{GS}

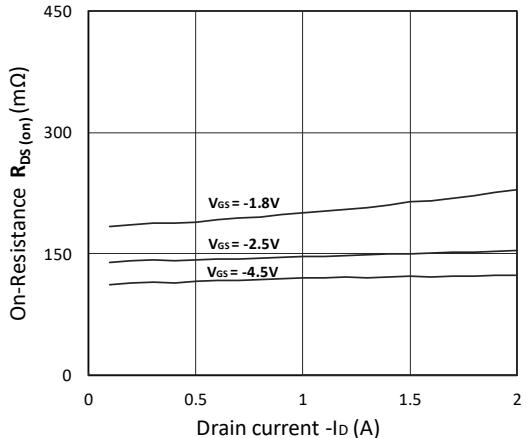


Figure 5. $R_{DS(on)}$ vs. I_D

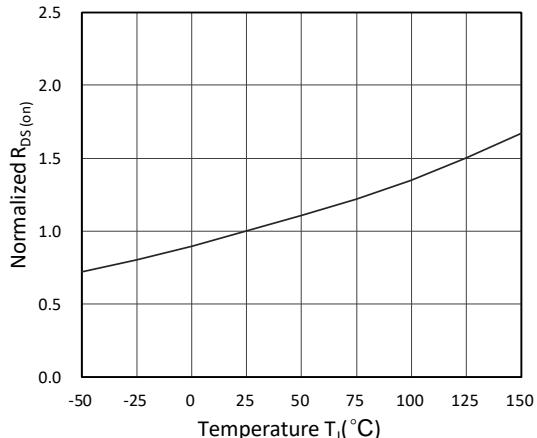
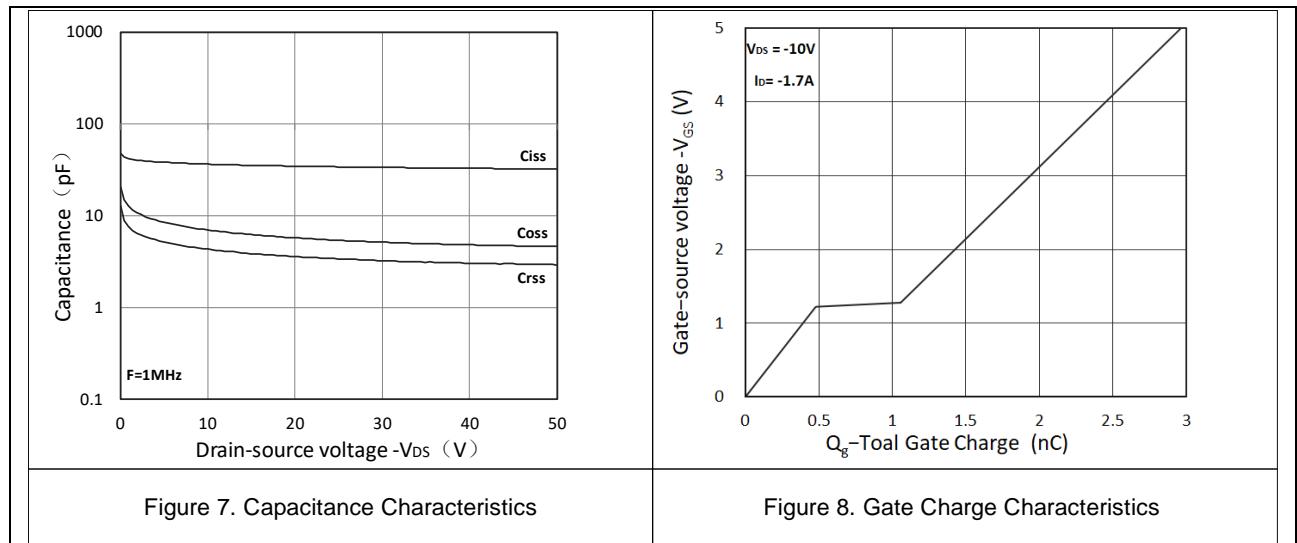


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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Typical Characteristics(Continued)



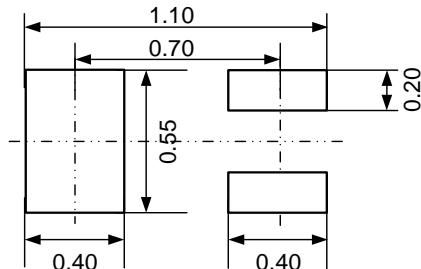
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Package Dimension

DFN1006-3L

PACKAGE OUTLINE		DFN1006-3L			
SYMBOL	MILLIMETER		INCHES		
	MIN	MAX	MIN	MAX	
A	0.45	0.55	0.018	0.022	
A1	0.00	0.05	0.000	0.002	
b	0.40	0.60	0.016	0.024	
B1	0.10	0.20	0.004	0.008	
D	0.95	1.05	0.037	0.041	
e	0.65BSC		0.026BSC		
E	0.55	0.65	0.022	0.026	
E1	0.19BSC		0.007BSC		
L	0.20	0.30	0.008	0.012	

Land Pattern



Ordering Information

Part	Package	Marking	Packing Information
EM02P18F	DFN1006-3L	01K	10k/Reel

EM02P18F

Revision History and Checking Table

Version	Date	Revision Item	Modifier	Function & Spec Checking	Package & Tape Checking
1.0	2022-08-17	Released Version	Chen Zu Xiong	Qi Shu Kun	Liu Jia Ying